## WOCSDICE - EXMATEC 2023

TIME	21 <sup>st</sup> May		22 <sup>nd</sup> May	23 <sup>rd</sup> May		24 <sup>th</sup> May		25 <sup>th</sup> May	
		Registration		4H-SiC device technology Session Chairs: F. Giannazzo, F. La Via				GaN devices & technology Session Chairs: G. Greco, Y. Cordier	
08:30					Recent trends in Schottky barriers for energy efficient silicon carbide power devices				
08:40				Marilena Vivona (Invited)				Joana Catarina Mendes (Invited)	Improving the performance of GaN HEMTs with diamond
08:50				(invited)	power devices				
09:00		Conference Opening		Marco Mauceri	200 mm Silicon Carbide Epitaxy	HEMTs Technology II Session Chairs: E. Zanoni, E. Piner		Youssef Hamdaoui	High quality drift layer thickness scaling in vertical GaN-on-Silicon PIN diodes
09:10			HEMTs Technology I nairs: F. Medjdoub, P. Fiorenza	Bart J. Van Zeghbroeck	Hot filament CVD growth and characterization of nitrogen-doped 4H-SiC	Yvon Cordier (Invited)	Past and new trends in the hetero- epitaxy of III-Nitrides for power devices	Sung-Hoon Lee	Design Methodology of Trench MIS Field Plate for GaN Vertical PN Diode
09:20	Srabanti Chowdhury (invited)	ury avalanche and thermal	Alfio Samuele Mancuso	Hydrogen etching process of 4H-SiC (0001) in limited regions			Mahmoud Abou Daher	Power Handling of GaN Schottky Diodes on Semi- Insulating Ammonothermal GaN Substrate at 94 GHz	
09:30		(		Aleš Chvála	Characterization of Electrical Properties of Power SiC Schottky Diodes	Reda Elwaradi	Epitaxial growth of AlGaN/GaN HEMTs on patterned Si substrate for high voltage power switching application	Seiya Kawasaki	Fabrication of GaN Hi-Lo IMPATT diode
09:40		Kei Sakota	Design of high-Al-content AlGaN/GaN HEMTs for improved DC and RF operation	Patrick Fiorenza	Time Dependent Dielectric Breakdown in 4H-SiC power MOSFETs under positive and negative gate- bias and gate-current stresses at 200°C	Vanya Darakchieva	Tunning composition in graded channel and high- Al content AlGaN barrier HEMTs	Pawel Prystawko	N-type sputtered GaN subcontact layers
09:50		Elodie Carneiro	Comparison of Sub-Micron thick AlGaN/GaN and AlN/GaN HEMTs on Silicon for RF applications	Bruno Galizia	Al2O3/AIN dielectric stacks for silicon carbide (4H- SiC) by Thermal and Plasma-Enhanced ALD growth	Etienne Nowak	Recent Achievements in Recessed Gate MOS- channel HEMT Technology	Zihao Lyu	Exploring the Effectiveness of Ni/ITO Ohmic Contact on p-Type GaN
10:00		Hossein Yazdani	Towards More Efficient Ka-band Power Cells: Low- Resistive Gate Module for RF GaN- HFETs by Electroplating	Carmen Altana	Heavy ions radiation damage on silicon and silicon carbide detectors	Joel T. Asubar	Threshold voltage control in GaN-based MIS- HEMTs with recessed structure and regrown AlGaN barrier layers	Camille Sonneville	Micro-Raman characterization of vertical GaN Schottky and PN diodes
10:10		Kathia Harrouche	Pushing Q-band power performances by means of buffer engineering in AIN-GaN HEMTs	Francesca Migliore	Response of epitaxial layer of 4H-SiC to $\beta$ -rays and X-rays irradiation	Jun-Hyeok Yim	Normally-off AlGaN/GaN MIS-HFET with AlN Passivation	Héctor Sánchez-Martín	Trap-related slow transient effects in AlGaN/GaN nanochannels at low temperature
10:20		Ryota Ochi	Influence of the parallel conduction on the current non-linearity of GaN based MIS-HEMTs in the forward bias region	Scott Greenhorn	4H-SiC N-P-N Epitaxial and Implanted Junctions for Isolation in Neural Interfaces			Dimitris Pavlidis	Vertical top-down GaN Nanowire Field Emitters with an Integrated Air-Bridge Anode Approach
10:30 - 11:00			Coffee Break		Coffee Break		Coffee Break	C	Coffee Break

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		Nitrides materials & defects Session Chairs: M. Leszczynski, E. Iliopulos		UWBG: Ga2O3 & ZnO Session Chairs: S. Besendoerfer, F. Lloret		UWBG: AIN & Diamond Session Chairs: S. Rajan, B. Pecz		Packaging and Applications of SiC & GaN devices Session Chairs: C. Giaconia, A. Chvala		
11:00								Nadia Lecci	How to exploit the intrinsic GaN technology features: application hints and integrated solutions performance evaluation	
11:10		Stefano Leone (Invited)	Status and Perspectives of AlScN Materials Grown by MOCVD	Siddharth Rajan (invited)	Device Engineering for Ultra-Wide Bandgap Semiconductors	Oliver Williams (invited)	Diamond Integration with non- diamond materials	Gregorio Iuzzolino	GaN based devices integration in the electric vehicle world	
11:20								Daniele Scirè	Comparison between SiC and GaN switching devices in fast-recharging systems for electric vehicles	
11:30		Yvon Cordier	Evaluation of the electrical properties of ScAIN/GaN HEMTs grown by ammonia source molecular beam epitaxy	Georges Brémond	Demonstration of a p/n junction behaviour using space charge spectroscopy in Zn:β-Ga2O3 grown by MOCVD	Beatriz Soto Portillo	ZrO2/diamond-based deep depletion MOSFET: electro-optical control of the threshold voltage	Giacomo Scelba	Performance Evaluation of GaN Technology on MultiLevel Inverters for Electric Traction Systems	
11:40		Alice Hospodková	Improvement of Electron Transport Properties in 2DEG bellow AlGaN/GaN interface by V-pit formation	Filip Tuomisto	Electrical compensation and vacancy defects in Si doped $\beta$ -(Al,Ga)2O3	Fernando Lloret	Effect of methane on phosphorus and nitrogen co doped CVD diamond growth	Giuseppe Galioto	GaN and SiC devices' input capacitance experimental characterization	
11:50		Matej Matus	Electrically Active Defects in InAlGaN/GaN HEMT structures	Marcell Gajdics	Study of the annealing-induced crystallization of Ga2O3 prepared by radio frequency sputtering	Joana C. Mendes	CVD diamond electrodes for in vitro electrophysiological sensing devices	Vincenzo Vinciguerra	Using ANSYS Finite Elements Analysis to Calculate the Equivalent Thickness of a Taiko Wafer	
12:00		Piotr Kruszewski	The Effect of Electric-Field Enhancement of Electron Emission Rates for Deep-Level Traps in n- type GaN	Carlos García Nuñez	Optimizing the Piezoelectric Response of Zinc Oxide Thin Films through Plasma Coating Deposition			Giuseppe Bellomonte	Corrosion study for RF power GaN HEMT in FO- WLP packaging	
12:10		Roger A. Peña	Temperature analysis of reverse leakage current hysteresis in GaN Schottky Barrier Diodes	Manuel Pelayo Garcia	On the quasi-static measurements of piezoelectric coefficient in semiconductor thin films for ultrasonic sensors	Sven Besendörfer (invited)	AlN for next generation power devices: from crystal growth to epitaxy			
12:20		Lucía Nieto Sierra	Study of AIN piezoelectric thin films deposited by reactive DC magnetron sputtering							
12:30-14:00		Light Lunch		Light Lunch		Light Lunch		Light Lunch		
		Other III-V compounds Session Chairs: D. Pavlidis, K. Zekentes		HEMTs Reliability Session Chairs: G. Meneghesso, H.J Würfl		Nitrides Quantum Wells Session Chairs: S. Leone, P. Prysawko		Industrial Session Session Chairs: F. Roccaforte		
14:00		Lorenzo Faraone	Dislocation filtering technology for defect reduction in heteroepitaxially-grown semiconductors		Microwave and millimeter-wave			Ferdinando lucolano		
14:10		Jonathan Hall	Logic Without CMOS: A III-V Semiconductor, Single Charge Carrier Approach to Digital Logic	Enrico Zanoni (invited)		David Cooper (invited)	Field mapping of IIIV semiconductor devices by off-axis electron holography	STMicroelectronics, Italy	GaN on Si Power and RF Technology: Devices and Application	
14:20		Vladimir Drakinskiy	Integrated Schottky Diode Mixer Technology up to 5 THz							
14:30		Pablo Caño	Room temperature pholuminescence of dilute (GaAs)1-x(Ge2)x ternary alloys	Giuseppe Greco	Correlation between gate current transport and degradation mechanisms in p-GaN-gate HEMTs	Eleftherios Iliopoulos	Surface kinetics mechanisms in RF-MBE epitaxy of InGaN alloys: The relative role of adsorption and decomposition concerning the entire ternary range	Sébastien Sicre (Keynote)	Characterization and model of dynamic R <sub>DSon</sub> drift of normally-off power GaN HEMTs	
14:40		Gilberto A. Umana Membreno	High-Resolution Mobility Spectrum Analysis of Electronic Transport in InAs/GaSb type-II Superlattices for Infrared Sensing Applications	Myeongsu Chae	Temperature dependence of the threshold voltage instability in normally-off AlGaN/GaN HEMTs with p-GaN gate	Mike Leszczynski	Diffusion of magnesium and silicon in AlGaInN			
14:50		Gizem Acar	Enhancing the efficiency of type-II GaSb quantum ring devices at telecommunication wavelengths using cavity effects	Giuseppe Luongo	Gate Leakage Transport Mechanism Analysis for p- GaN Power HEMTs	Ewa Grzanka	Temperature induced structural and optical changes in InGaN/GaN Quantum Wells			
15:00		Samuel Jones	Distributed Bragg Reflectors for GaSb/GaAs Quantum-Ring Vertical-Cavity Surface-Emitting Lasers Targeting Telecommunications and Sensing	Maurizio Moschetti	Temperature Effect on RON-degradation induced by Off-state Drain Voltage Stress	Marco Nicoletto	InGaN/GaN Multiple Quantum Wells solar cells: a trade-off in p-GaN thickness, to optimize reliability and quantum efficiency			
15:10		Nima Dehdashtiakhavan	High performance HgCdTe short-wave infrared detectors for emerging sensing and imaging applications	Giovanni Giorgino	Improved High Temperature Behaviour of On- Resistance in 100V p-GaN HEMTs	Mikolaj Grabowski	The influence of point defects present in the substrates with different TDD after ion implantation on InGaN/GaN QWs properties and stability at high temperatures	Student Awards Cerimony & Closing Remarks		
15:20		Xiuxin Xia	An Optimised Fabrication Flow for Scaling of ULTRARAM™ Devices	Nicolò Zagni	Modelling and Simulation of ON-Resistance Instability due to Gate Bias in p-GaN Power HEMTs	Hoi Wai Choi	Integration of GaN-based optoelectronic devices with Si-based integrated circuits			

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15:30 - 16:00		Coffee Break		Cristina Miccoli	Dynamic RDS-on degradation analysis on power GaN HEMT by means of TCAD simulations and experimental measurement.	Coffee Break		
16:00		Sessio	<b>2D Materials</b> n Chairs: J.C. Mendes, J. Sun		Coffee Break		<b>pic Silicon Carbide (3C-SiC)</b> O Chairs: D. Alquier, M. Vivona	
16:10		Sebastian Pazos (Invited)	Hexagonal boron nitride as two- dimensional functional layered insulator: from fundamentals to true random number generation			Jean-François Michaud (Invited)	3C-SiC MEMS for gas detection	
16:20 16:30		Béla Pécz	Highly uniform MoS2 heterojunctions with bulk GaN by sulfurization of ultrathin MoOx film			Francesco La Via	Measurement of residual stress, Young's modulus and beam resonator Q factor on micromachined monocrystalline 3C-SiC layers grown on <111> silicon	
16:40		Filippo Giannazzo	Towards large area MoS2 heterostructures with epitaxial graphene on SiC			Viviana Scuderi	Effect of stress on 3C-SiC resonator by Raman spectroscopy.	-
16:50		Salvatore Ethan Panasci	Highly crystalline monolayer MoS2 on sapphire by sulfurization of Molybdenum oxide ultrathin films			Emanuela Schilirò	Al2O3 layers grown by Atomic Layer Deposition as gate insulator in 3C-SiC MOS devices Growth of High-Quality Cubic Silicon Carbide and	
17:00		Simonpietro Agnello	Aging effects and thermally induced modification of monolayer MoS2 obtained by gold assisted exfoliation			Jianwu Sun	Graphene for Conversion of Solar Energy into Renewable Fuels	
17:10		Jozef Novák	Bipolar heterojunction phototransistor based on thin PtSe2 layer					
17:20		Emma Keel	Three-dimensional graphene foam for energy harvesting devices					
17:30		Zsofia Baji	VO2 layers prepared with different approaches: relationship between resistive switching and structural properties	Excu	rsion and Social dinner			
17:40		Marco Cannas	Graphitization effects induced by thermal treatments of 4H-SiC					
17:50		Zsofia Baji	Nucleation of atomic layer deposited metal sulphide layers					
18:00 - 19:00	Registration	-						
19:00 - 21:00	Welcome reception							
21:00 - 23:00								